



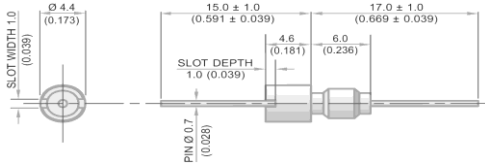
# Feedthrough EMI Filter Datasheet

(6-32 UNC Thread : 4.4mm Round Head)

## Circuit Configurations Available



Dimensions mm (inches)



6-32 UNC Class 2A Thread

Electrical Details	
Electrical Configuration	C Filter
Capacitance Measurement	@ 1000hr Point
Current Rating	10A
Insulation Resistance (IR)	10GΩ or 1000ΩF
Temperature Rating	-55°C to +125°C
Ferrite Inductance (Typical)	See relevant tables
Mechanical Details	
Head Diameter	4.4mm (0.173")
Nut A/F	N/a. For use in tapped hole
Washer Diameter	N/a
Mounting Torque	0.15Nm (1.32lbf in) max.
Mounting Hole	6-32 UNC Class 2B
Max. Panel Thickness	N/a
Weight (Typical)	0.8g (0.03oz)
Finish	Silver plate on copper undercoat

## C Configuration

Product Code	Capacitance ± 20% UOS	Dielectric	Rated Voltage (dc)	DWV (dc)	Typical Insertion Loss (db)					
					0.01MHz	0.1MHz	1MHz	10MHz	100MHz	1GHz
* SFKBC5000100ZC0	10pF -20% / +80%	C0G	500#	750						4
SFKBC5000150ZC0	15pF -20% / +80%	C0G	500#	750						7
SFKBC5000220ZC0	22pF -20% / +80%	C0G	500#	750						10
SFKBC5000330ZC0	33pF -20% / +80%	C0G	500#	750						12
* SFKBC5000470ZC0	47pF -20% / +80%	C0G	500#	750					1	15
* SFKBC5000680MC0	68pF	C0G	500#	750					2	18
* SFKBC5000101MC0	100pF	C0G	500#	750					4	22
SFKBC5000151MC0	150pF	C0G	500#	750					7	25
* SFKBC5000221MC0	220pF	C0G	500#	750					10	29
* SFKBC5000331MC0	330pF	C0G	500#	750					13	33
* SFKBC5000471MX0	470pF	† X7R	500#	750				1	16	35
SFKBC5000681MX0	680pF	† X7R	500#	750				2	19	36
* SFKBC5000102MX0	1.0nF	X7R	500#	750				4	23	41
SFKBC5000152MX0	1.5nF	X7R	500#	750				7	26	45
* SFKBC5000222MX0	2.2nF	X7R	500#	750				10	30	50
SFKBC5000332MX0	3.3nF	X7R	500#	750				13	33	52
* SFKBC5000472MX0	4.7nF	X7R	500#	750			1	16	36	55
SFKBC5000682MX0	6.8nF	X7R	500#	750			2	19	39	57
* SFKBC5000103MX0	10nF	X7R	500#	750			4	22	41	60
* SFKBC5000153MX0	15nF	X7R	500#	750			7	25	44	62
* SFKBC5000223MX0	22nF	X7R	500#	750			10	29	46	65
SFKBC5000333MX0	33nF	X7R	500#	750			13	33	48	68
* SFKBC2000473MX0	47nF	X7R	200	500		1	16	35	50	70
SFKBC2000683MX0	68.0nF	X7R	200	500		2	19	39	54	>70
*SFKBC1000104MX0	100nF	X7R	100	250		4	22	41	57	>70
*SFKBC0500154MX0	150nF	X7R	50	125		7	25	45	60	>70

# - Also rated for operation at 115Vac 400Hz. Self-heating will occur – evaluation in situ recommended

\* Recommended values

† Also available in C0G



## L-C Configuration

Ferrite Inductance (Typical) – 50nH					Typical Insertion Loss (db)					
Product Code	Capacitance ± 20% UOS	Dielectric	Rated Voltage (dc)	DWV (dc)	0.01MHz	0.1MHz	1MHz	10MHz	100MHz	1GHz
*SFKBL5000100ZC0	10pF -20% / +80%	COG	500#	750						6
SFKBL5000150ZC0	15pF -20% / +80%	COG	500#	750						9
SFKBL5000220ZC0	22pF -20% / +80%	COG	500#	750						12
SFKBL5000330ZC0	33pF -20% / +80%	COG	500#	750					1	15
*SFKBL5000470ZC0	47pF -20% / +80%	COG	500#	750					2	19
*SFKBL5000680MC0	68pF	COG	500#	750					4	20
*SFKBL5000101MC0	100pF	COG	500#	750					7	24
SFKBL5000151MC0	150pF	COG	500#	750					10	27
*SFKBL5000221MC0	220pF	COG	500#	750					12	30
*SFKBL5000331MC0	330pF	COG	500#	750				1	16	34
*SFKBL5000471MX0	470pF	† X7R	500#	750				2	19	38
SFKBL5000681MX0	680pF	† X7R	500#	750				3	22	41
*SFKBL5000102MX0	1.0nF	X7R	500#	750				6	25	44
SFKBL5000152MX0	1.5nF	X7R	500#	750				9	29	48
*SFKBL5000222MX0	2.2nF	X7R	500#	750				12	31	51
SFKBL5000332MX0	3.3nF	X7R	500#	750				15	35	54
*SFKBL5000472MX0	4.7nF	X7R	500#	750			1	18	39	57
SFKBL5000682MX0	6.8nF	X7R	500#	750			2	21	41	60
*SFKBL5000103MX0	10nF	X7R	500#	750			4	23	43	63
*SFKBL5000153MX0	15nF	X7R	500#	750			7	27	46	66
*SFKBL5000223MX0	22nF	X7R	500#	750			10	30	48	68
SFKBL5000333MX0	33nF	X7R	500#	750			13	34	50	70
*SFKBL2000473MX0	47nF	X7R	200	500		1	17	37	51	>70
SFKBL2000683MX0	68nF	X7R	200	500		2	20	40	55	>70
*SFKBL1000104MX0	100nF	X7R	100	250		4	22	44	60	>70
*SFKBL0500154MX0	150nF	X7R	50	125		7	25	47	62	>70

# - Also rated for operation at 115Vac 400Hz. Self-heating will occur – evaluation in situ recommended

\* Recommended values

† Also available in COG

## Ordering Information

Type	Case Style	Thread	Electrical configuration	Voltage (dc)	Capacitance in picofarads (pF)	Capacitance Tolerance	Dielectric	Hardware
SF	K	B	C	500	0102	M	X	0
Syfer Filter	4.4mm O.D.	6-32 UNC	C = C Filter L = L-C Filter	050 = 50V 100 = 100V 200 = 200V 500 = 500V	First digit is 0. Second and third digits are significant figures of capacitance code. The fourth digit is the number of zeros following. Examples: 0101 = 100pF 0332 = 3300pF	M = ± 20% Z = -20+80%	C = COG/NPO X = X7R	0 = Without

Note<sup>1</sup>: Installation tool available on request

Note<sup>2</sup>: The addition of a 4-digit numerical suffix code can be used to denote changes to the standard part.

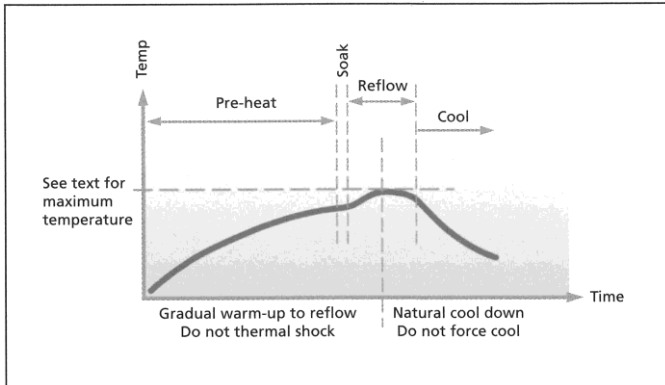
Options include for example: change of pin length / custom body dimensions or threads / alternative voltage rating / non-standard intermediate capacitance values / test requirements.

Please refer specific requests to the factory.

## Surface Mount and Panel Mount Solder-in filters

Solder pad layouts are included with the detailed information for each part.

### Recommended soldering profile



### Soldering of filters

The soldering process should be controlled such that the filter does not experience any thermal shocks which may induce thermal cracks in the ceramic dielectric.

The pre-heat temperature rise of the filter should be kept to around 2°C per second. In practice successful temperature rises tend to be in the region of 1.5°C to 4°C per second dependent upon substrate and components.

The introduction of a soak after pre-heat can be useful as it allows temperature uniformity to be established across the substrate thus preventing substrate warping. The magnitude or direction of any warping may change on cooling imposing damaging stresses upon the filter.

E01, E03, E07 SBSP ranges are compatible with all standard solder types including lead-free, maximum temperature 260°C. For SBSG, SBSM and SFSS ranges, solder time should be minimised, and the temperature controlled to a maximum of 220°C. For SFSR, SFST and SFSU ranges the maximum temperature is 250°C.

Cooling to ambient temperature should be allowed to occur naturally. Natural cooling allows a gradual relaxation of thermal mismatch stresses in the solder joints. Draughts should be avoided. Forced air cooling can induce thermal breakage, and cleaning with cold fluids immediately after a soldering process may result in cracked filters.

Note: The use of FlexiCap™ terminations is strongly recommended to reduce the risk of mechanical cracking.

### Soldering to axial wire leads

#### Soldering temperature

The tip temperature of the iron should not exceed 300°C.

#### Dwell time

Dwell time should be 3-5 seconds maximum to minimise the risk of cracking the capacitor due to thermal shock.

#### Heat sink

Where possible, a heat sink should be used between the solder joint and the body, especially if longer dwell times are required.

### Bending or cropping of wire leads

Bending or cropping of the filter terminations should not be carried out within 4mm (0.157") of the epoxy encapsulation, the wire should be supported when cropping.

**Soldering irons should not be used for mounting surface mount filters as they can result in thermal shock damage to the chip capacitor.**

**A more comprehensive application note covering installation of all Syfer products is available on the Syfer website.**

## Resin filled screw mounted EMI filters

### General

The ceramic capacitor, which is the heart of the filter, can be damaged by thermal and mechanical shock, as well as by over-voltage. Care should be taken to minimise the risk of stress when mounting the filter to a panel and when soldering wire to the filter terminations.

### Mounting to chassis

#### Mounting torque

It is important to mount the filter to the bulkhead or panel using the recommended mounting torque, otherwise damage may be caused to the capacitor due to distortion of the case. When a threaded hole is to be utilised, the maximum mounting torque should be 50% of the specified figure which relates to unthreaded holes. For details of torque figures for each filter range, please see below.

Thread	Torque (max.)	
	With nut	Into tapped hole
M2.5 & 4-40 UNC	-	0.15Nm (1.32lbf in)
M3	0.25Nm (2.21lbf in)	0.15Nm (1.32lbf in)
6-32 UNC	0.3Nm (2.65lbf in)	0.15Nm (1.32lbf in)
M3.5	0.35Nm (3.09lbf in)	0.18Nm (1.59lbf in)
M4 & 8-32 UNC	0.5Nm (4.42lbf in)	0.25Nm (2.21lbf in)
M5, 12-32 UNEF & 2BA	0.6Nm (5.31lbf in)	0.3Nm (2.65lbf in)
M6 & 1/4-28 UNF	0.9Nm (7.97lbf in)	-

### Tools

Hexagonal devices should be assembled using a suitable socket. Round bodied filters may be fitted to the panel in one of two ways (and should not be fitted using pliers or other similar tools which may damage them):

- Round bodies with slotted tops are designed to be screwed in using a simple purpose-designed tool.
- Round bodies without slotted tops are intended to be inserted into slotted holes and retained with a nut.

### Grounding

To ensure the proper operation of the filters, the filter body should be adequately grounded to the panel to allow an effective path for the interference. The use of locking adhesives is not recommended, but if used should be applied after the filter has been fitted.

#### Minimum plate thickness

Users should be aware that the majority of these filters have an undercut between the thread and the mounting flange of the body, equal to 1.5 x the pitch of the thread. Mounting into a panel thinner than this undercut length may result in problems with thread mating and filter position. It is recommended that a panel thicker than this undercut length be used wherever possible.

#### Maximum plate thickness

This is specified for each filter in order that the nut can be fully engaged even when using a washer.

### Soldering to axial wire leads

#### Soldering temperature

The tip temperature of the iron should not exceed 300°C.

#### Dwell time

Dwell time should be 3-5 seconds maximum to minimise the risk of cracking the capacitor due to thermal shock.

#### Heat sink

Where possible, a heat sink should be used between the solder joint and the body, especially if longer dwell times are required.

### Bending or cropping of wire leads

Bending or cropping of the filter terminations should not be carried out within 4mm (0.157") of the epoxy encapsulation, the wire should be supported when cropping.

### RoHS compliance

All surface mount filters, resin sealed panel mount filters and power filters are fully RoHS compliant through material exemption, although care must be taken not to exceed the maximum soldering temperatures of surface mount parts.

Standard hermetic sealed panel mount filters use SnPb solders as part of their assembly, and are intended for exempt applications such as aerospace or military. Substitution of the SnPb solder with Pb free solders is possible to create a RoHS compliant part – please contact factory for further details.